

ABSTRACT OF THE DISCLOSURE

A semiconductor device has a first semiconductor chip and a second semiconductor chip superposed on and bonded to the surface of the first semiconductor chip. In the region on the first semiconductor chip where the
5 second semiconductor chip is bonded thereto, connection pads are arranged in positions that fit a plurality of predetermined types of semiconductor chips. On the second semiconductor chip, connection pads are arranged in positions that fit the connection pads arranged on the first semiconductor chip.